

IN THE CLAIMS

Claim 1 (currently amended). An adhesive sheet composed formed of an adhesive system comprising of a mixture of two thermoplastics T1 and T2, wherein the adhesive system has

- a) the adhesive system has a softening temperature of greater than 65°C and less than 125°C,
- b) a storage modulus G' at 23°C, as measured by test method A, of greater than 10<sup>7</sup> Pas,
- c) a loss modulus G" at 23°C, as measured by test method A, of greater than 10<sup>6</sup> Pas,
- d) and a crossover, as measured by test method A, of less than 125°C.

Claim 2 (currently amended). The adhesive sheet of claim 1, characterized in that wherein the layer thickness is between 10 and 100 µm, with particular preference between 30 and 80 µm.

Claim 3 (currently amended). The adhesive sheet of at least one of the preceding claims, characterized in that claim 1, wherein thermoplastics T1 and T2 are selected from the groups group consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 4 (currently amended). The adhesive sheet of at least one of the preceding claims, characterized in that reactive resins used additionally comprise claim 1, wherein said adhesive system further comprises reactive resins selected from the group consisting of epoxy resins, and/or phenolic resins and/or novolak resins and combinations thereof.

Claim 5 (currently amended). The use of an adhesive sheet of any one of the above claims A method for bonding chip modules in card bodies which comprises bonding said chip modules in said card bodies with the adhesive sheet of claim 1.

Claim 6 (currently amended). ~~The use of an adhesive sheet of any one of the above claims for bonding~~ method of claim 5, wherein said chip modules are polyimide-, polyester or epoxy-based chip modules and ~~on~~ said card bodies are PVC, ABS, PET, PC, PP or PE card bodies.

Claim 7 (currently amended). A method for producing a heat-activable adhesive tape, ~~characterized in that an~~ which comprises coating the adhesive sheet of ~~claims 1 to 4 is coated~~ claim 1 onto a release paper or a release film.

Claim 6 ~~8~~ (currently amended). The method of claim 7, ~~characterized in that~~ wherein the heat-activable adhesive tape is die-cut.

Claim 7 ~~9~~ (currently amended). ~~The method of at least one of the preceding claims, characterized in that the heat-activable adhesive tape is processed with~~ A method for implanting a chip module in a card body, which comprises implanting said chip module in said card body with a heat activable adhesive tape comprised of the adhesive sheet of claim 1 coated onto a release paper or release film, and an implanter having an implanting die at an implanting die temperature of 150°C.

Claim 10 (new). The adhesive sheet of claim 2, wherein said layer thickness is between 30 and 80 µm.